

IN THE CLAIMS:

Please amend the claims as follows.

Claim 1 (Currently Amended): A wiring substrate, having ~~[[a]]~~ conduction ~~paths~~ path that guide an electrical signal between a signal input surface and a signal output surface,

the wiring substrate comprising at least a first wiring substrate, disposed at the signal input surface side, and a second wiring substrate, connected to the first wiring substrate at the signal output surface side, each wiring substrate respectively comprising a glass substrate, formed of a predetermined glass material having a radiation shielding function and provided with ~~[[a]]~~ through ~~[[hole]]~~ holes, and ~~[[a]]~~ conductive ~~member~~ members, disposed in the through ~~[[hole]]~~ holes and functioning as the conduction ~~[[path]]~~ paths by providing electrical continuity between the input surface and the output surface, and

wherein in the view in the conduction direction from the signal input surface to the signal output surface, the ~~positions~~ position of the through ~~[[hole]]~~ holes in the first wiring substrate ~~differs~~ differ from the ~~position~~ positions of the through ~~[[hole]]~~ holes in the second wiring substrate, and

the through holes and the conductive members in the second wiring substrate are formed at a pitch which is smaller than a pitch of the through holes and the conductive members in the first wiring substrate.

Claim 2 (Original): The wiring substrate according to Claim 1, wherein each of the first wiring substrate and the second wiring substrate is formed of the glass material that contains lead.

Claim 3 (Previously Presented): The wiring substrate according to Claim 1, wherein the conductive member of each of the first wiring substrate and second wiring substrate is formed and disposed on the inner wall of the through hole that is provided in the glass substrate.

Claim 4 (Previously Presented): The wiring substrate according to Claim 1, wherein the conductive member of each of the first wiring substrate and second wiring substrate is disposed by filling the interior of the through hole that is provided in the glass substrate.

Claim 5 (Previously Presented): The wiring substrate according to Claim 1, wherein the glass substrate of each of the first wiring substrate and second wiring substrate is a glass substrate, wherein a plurality of the through holes are provided by fusing together and integrally forming a plurality of hollow glass members that are open at both ends.

Claim 6 (Withdrawn): A radiation detector comprising:

a radiation detecting means, outputting a detected signal upon detecting radiation made incident thereon;

a signal processing means, processing the detected signal from the radiation detecting means; and

a wiring substrate section, having the wiring substrate according to Claim 1 that is provided with the conduction path that guide the detected signal between the signal input surface and the signal output surface, the radiation detecting means and the signal processing means being connected to the signal input surface and the signal output surface, respectively; and

wherein the radiation detecting means, the wiring substrate section, and the signal processing means are positioned in that order along a predetermined alignment direction that substantially matches the conduction direction in the wiring substrate.

Claim 7 (Withdrawn): The radiation detector according to Claim 6, wherein the radiation detecting means comprises a scintillator, generating scintillation light upon incidence of radiation; and a semiconductor photodetecting element, detecting the scintillation light from the scintillator.

Claim 8 (Withdrawn): The radiation detector according to Claim 6, wherein the radiation detecting means comprises a semiconductor detecting element, detecting radiation made incident thereon.

Claim 9 (Withdrawn): The radiation detector according to Claim 6, wherein at least one of either the combination of the wiring substrate section and the radiation detecting means or the combination of the wiring substrate section and the signal processing means is electrically connected via a bump electrode.

Claim 10 (New): The wiring substrate according to Claim 1, wherein the conductive members of the first wiring substrate are electrically connected to the corresponding conductive members of the second wiring substrate via bump electrodes,

the bump electrodes are electrically connected directly to output portions, formed on the output surface of the first wiring substrate, of the corresponding conductive members of the first

wiring substrate, and

the bump electrodes are electrically connected via wirings to input portions, formed on the input surface of the second wiring substrate, of the corresponding conductive members of the second wiring substrate.

Claim 11 (New): The wiring substrate according to Claim 1, wherein, in addition to input portions of the conductive members, electrode pads electrically connected via wirings to the input portions of the corresponding conductive members are formed on the input surface of the first wiring substrate.